

MACHINING QUALITY JUDGING METHOD FOR WAFER GRINDING
MACHINE AND WAFER GRINDING MACHINE

5

ABSTRACT OF THE DISCLOSURE

10 A machining quality judging method for a wafer
grinding machine and wafer grinding machine are
disclosed. The thickness of a wafer 2 is acquired from
the feed amount of a grinding unit 3 while at the same
time actually measuring the thickness of the wafer 2
appropriately. The wafer grinding machine includes a
15 machining quality judging unit 20 for comparing the
thickness of the wafer 2 based on the feed amount of the
grinding unit 3 with the actually measured thickness of
the wafer 2 and judges the machining quality of the
ground surface of the wafer 2. Upon judgment of a
20 machining failure, a command is issued to stop the back
surface grinding operation.

Figure. 1